

→ Our Sales Team reinforced and fully at your service!

SET has restructured and reinforced strongly its sales Team. Of course, renowned contact people from SET like Pascal, Jean-Stephane, Caroline, Denis, Virginie and Catherine are still there and fully dedicated to customers. During 2015, the Service team has been significantly reinforced thanks to the arrival of two new engineers: **Francois Chabrerie** and **Matthew Fournet**.

And now, we are pleased to welcome **Pascal Um** who joined our team at the beginning of February 2016 as a Business Development Manager. He is in charge of global sales and contributes to grow SET's Business Networking worldwide.



→ ACCμRA100: More capabilities



According to R&D of the University of Geneva/CERN's feedbacks, the ACCμRA100 had been proven to be the perfect equipment focused on a high force machine (1 to 1000 N).

Now SET will introduce at SMT Nürnberg-Germany by end of April, its little sister **ACCμRA OPTO** (0.2 to 10 N) dedicated to optoelectronic, photonics applications and more in general any application requiring very low forces during bonding (i.e. laser and photo diodes, laser bars, VCSELs, LEDs...). **ACCμRA100** will offer then a complete range of configurations to cover all our customer needs. **It is the perfect equipment for universities and R&D institutes.**

→ SET equipment: Introduction of the High Volume Manufacturing machine

After 35 years manufacturing high accuracy flip-chip bonders, as well as 41 years of various equipment, SET is now pleased to offer a smart equipment targeted on both high accuracy and high throughput. At 3D Summit in Grenoble on January 19/20th this year, SET has officially announced its new equipment for production which the main specifications are 1000 bonds per hour within +/- 1 μm accuracy. The leading sectors are clearly the **3D-IC/3D-TSV** and the **Silicon Photonics** integration, using a chip-to-wafer approach.

Meanwhile, SET announced the signature of a technical agreement with CEA-LETI to qualify this new equipment with real applications in a production mode. "All SET employees, and in particular the team involved in the 3D project, are proud and enthusiastic to join IRT Nanoelec" said Pascal Metzger, CEO of SET. "Our integration in this program is a logical continuation of the collaboration initiated with CEA teams 35 years ago on different bonding projects, including laboratory high-precision bonder for Cu-Cu direct bonding. One of the key factors joining this consortium is the opportunity to meet and discuss with experts from different specialties."

On the other hand, Séverine Chéramy, director of IRT Nanoelec's 3D integration program, said the objective is to offer designers 3D die-to-wafer stacking at an aggressive pitch – less than 10 μm – at high speed, at room temperature and without pressure or underfill.

For more detail regarding SET joins IRT Nanoelec 3D Integration Program, please link at <http://www.set-sas.fr/en/mpg2-793209--SET-is-proud-to-announce-a-new-and-important-partnership.html>

→SET labeled BPI Excellence 2016



SET was chosen by BPI France to be certified BPI Excellence this year and, to help its growth and the various technical development projects, has contracted several partnerships. One of them has been signed with BPI France (Banque Publique d'Investissement), French bank specialized in innovative, technical and industrial activities. SET is proud to have been selected as an innovative, reliable, international and growing company, permitting it to be labeled as BPI France Excellence for this year.

→Exhibitions and Conferences: when and where meeting SET in 2016

SET already attended to **Semicon Korea** this year with the kind and appreciated support of our local agent Woowon.

SET was also represented at **NEPCON Japan 2016** thanks to our local agent Asahi Techno Solutions.

We were also present at the **European 3D Summit** in France where SET presented a paper during these conferences: the subject was "**The future of 3D Integration design and manufacturing**".

In addition **SET** will take part, with the kind collaboration of our local agents, to the forthcoming fairs and conferences:

- **Semicon China** (Shanghai - China) - March 15/17th
- **SMT** (Nürnberg, Germany) – April 26/29th
- **ECTC** (Las Vegas, USA) from May 31st/June 3rd
- **Semicon West** (San Francisco – USA) - July 12/14th
- **Semicon Taiwan** (Taipei – Taiwan) - September 7/9th
- **ESTC** (Grenoble – France) - September 13/16th
- **Micronora** (Besancon – France) - September 27/29th
- **Semicon Europa** (Grenoble – France) - October 25/27th
- **Semicon Japan** (Tokyo – Japan) - December 14/16th



Productronica 2015

We will present our latest machines, developments and technical support soon and thank you for your attention.